PCN Number:	20230522003.1	PCN Date:	May 24, 2023
Title:	Qualification of CFAB and DFAB8 as additional Fab sites for Select LBC4 Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Aug 24, 2023	Sample requests accepted until:	Jun 24, 2023*

***Sample requests received after Jun 24, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☒	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Qualification of additional Fab sites (CFAB & DFAB8) using qualified Process Technology for the list of devices in the product affected section below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
DL-LIN	LBC4	150mm	CFAB DL-LIN	LBC4	200mm

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

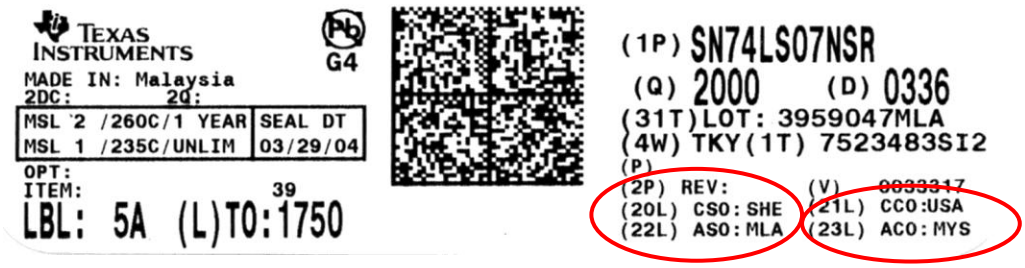
RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
CFAB	**CU3**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)



Product Affected:			
UCC2897APW	UCC2897APWR	UCC2897ARGPR	UCC2897ARGPT
UCC2897APW/1	UCC2897APWR/1		

For alternate parts with similar or improved performance, please visit the product page on TI.com

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65HVDA1040AQDRQ1
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/135/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	3/2400/0
HBM	ESD - HBM	4000 V	1/3/0
HBM	ESD - HBM (Pin 5)	10000 V	1/3/0
HBM	ESD - HBM (Pin 6 & 7)	12000 V	1/3/0
CDM	ESD - CDM	1500 V	1/3/0
LU	Latch-up	(per JESD78)	1/6/0
ED	Electrical Distributions	Per Datasheet parameters	3/90/0

- QBS: Qual by Similarity
- Qual Device SN65HVDA1040AQDRQ1 qualified at LEVEL1-260C

A1 (PC): Preconditioning:
Performed for THB, Biased HAST, AC, uHAST, TC & PTC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40°C to +150°C
Grade 1 (or Q): -40°C to +125°C
Grade 2 (or T): -40°C to +105°C
Grade 3 (or I): -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold: HTOL, ED
Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room: AC/uHAST

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20170424-121679

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC2897APWR	QBS Process Reference: TLC5970RHPR	QBS Package Reference: TPS53123PW	QBS Package Reference: SN74LVT574PW
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-	
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HBM	ESD - HBM	2500 V	1/3/0	-	-	-
HBM	ESD - HBM	2000 V		3/9/0		
CDM	ESD - CDM	1500 V	1/3/0	-	-	-
CDM	ESD - CDM	500 V	-	3/9/0	-	-
LU	Latch-up	(per JESD78)	1/3/0	3/18/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity
- Qual Device UCC2897APWR is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2302-053

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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